TITLE: Method of Modulating Surface Mount Technology Solder Volument Politics Peliability and Fine Pitch Yield

INVENTOR(S): Richard C. Blish II, et al. SERIAL NO. (IF KNOWN): 09/822,562

DOCKET NO. PJW 126 NAME & TELEPHO OF PERSON TO CALL IF NECESSARY: Paul J. Winters (650) 961-5658 SHEET 1 OF 8

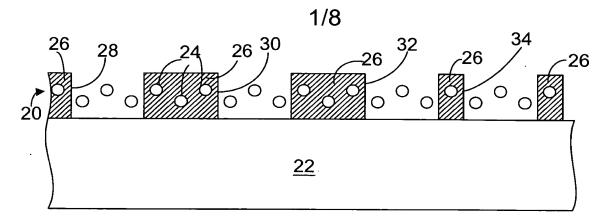
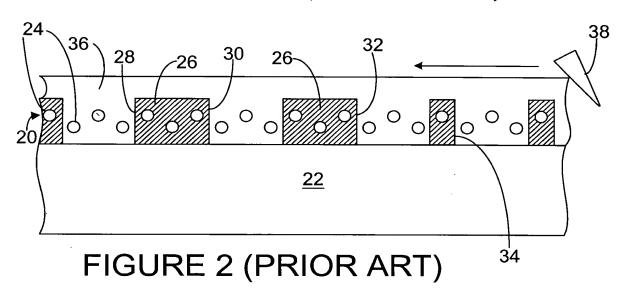


FIGURE 1 (PRIOR ART)



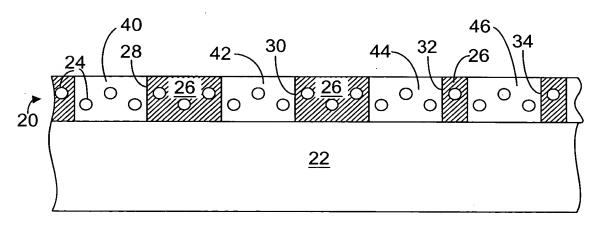


FIGURE 3 (PRIOR ART)

TITLE: Method of Modulating Surface Mount Technology Solder Volument Primize Reliability and Fine Pitch Yield

INVENTOR(S): Richard C. Blish II, et al. SERIAL NO. (IF KNOWN): 09/822,562

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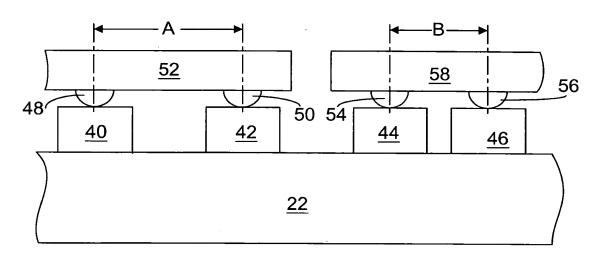


FIGURE 4 (PRIOR ART)

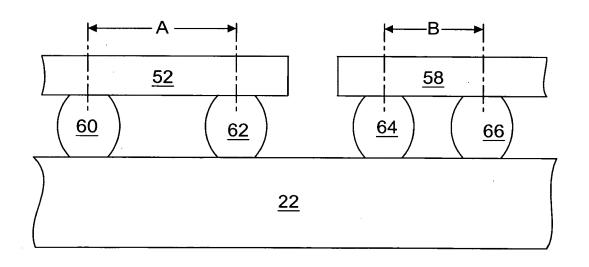


FIGURE 5 (PRIOR ART)

TITLE: Method of Modulating Surface Mount Technology Solder Volument Potimize Reliability and Fine Pitch Yield

INVENTOR(S): Richard C. Blish II, et al. SERIAL NO. (IF KNOWN): 09/822,562

DOCKET NO. PJW 126 NAME & TELEPHO IF NECESSARY: Paul J. Winters (650) 961-5658 SHEET 3 OF 8

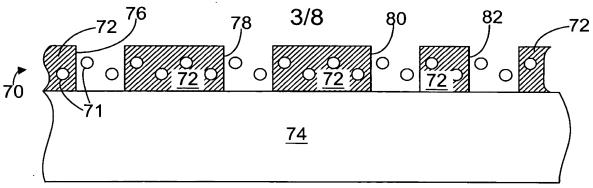


FIGURE 6 (PRIOR ART)

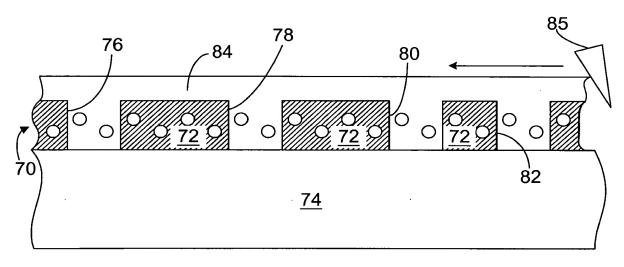


FIGURE 7 (PRIOR ART)

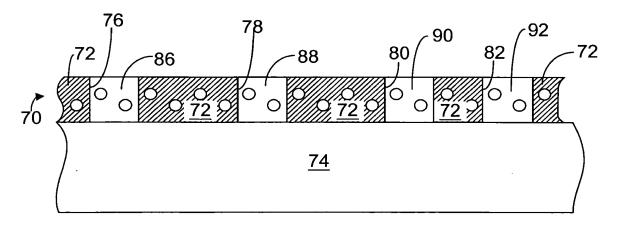


FIGURE 8 (PRIOR ART)

TITLE: Method of Modulati Turface Mount Technology Solder Volume Optimize Reliability and Fine Pitch Yield

INVENTOR(S): Richard C. Blish II, et al. SERIAL NO. (IF KNOWN): 09/822,562

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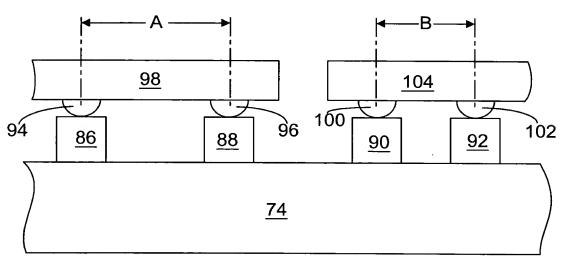


FIGURE 9 (PRIOR ART)

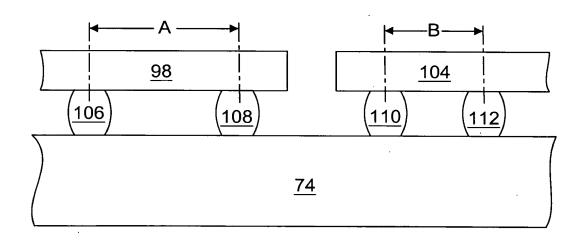


FIGURE 10 (PRIOR ART)

TITLE: Method of Modulat Surface Mount Technology Solder Volume Optimize Reliability and Fine Pitch Yield

INVENTOR(S): Richard C. Blish II, et al. SERIAL NO. (IF KNOWN): 09/822,562

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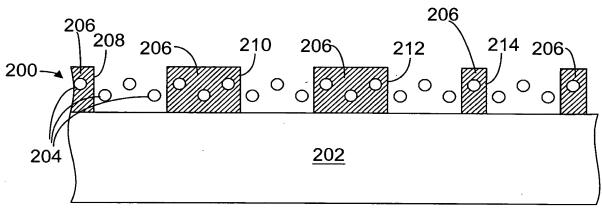


FIGURE 11

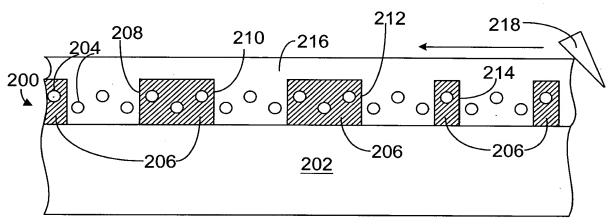


FIGURE 12

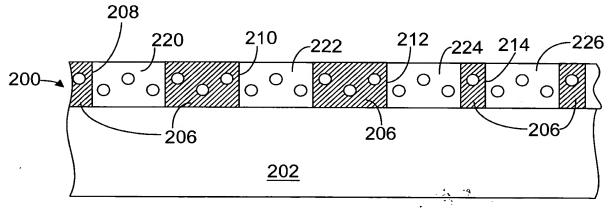


FIGURE 13

TITLE: Method of Modulati Curface Mount Technology Solder Voluand Optimize Reliability and Fine Pitch Yield

INVENTOR(S): Richard C. Blish II, et al. SERIAL NO. (IF KNOWN): 09/822,562

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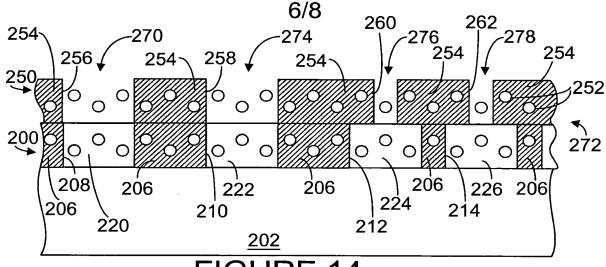


FIGURE 14

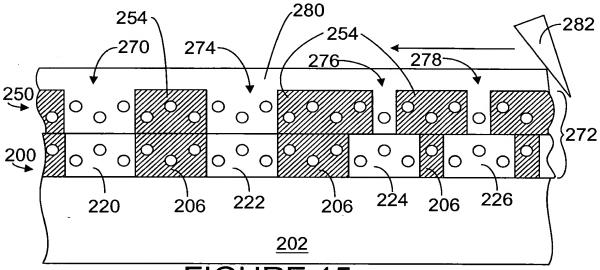


FIGURE 15

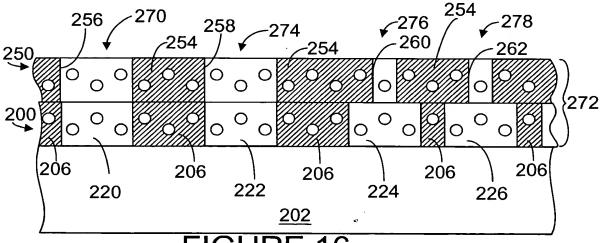


FIGURE 16

TITLE: Method of Modulation Surface Mount Technology Solder Volume Optimize Reliability and Fine Pitch Yield

INVENTOR(S): Richard C. Blish II, et al. SERIAL NO. (IF KNOWN): 09/822,562

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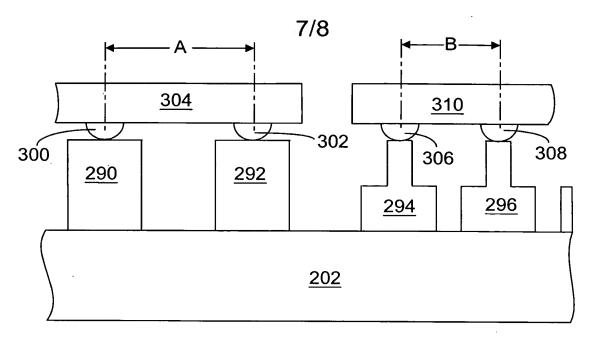


FIGURE 17

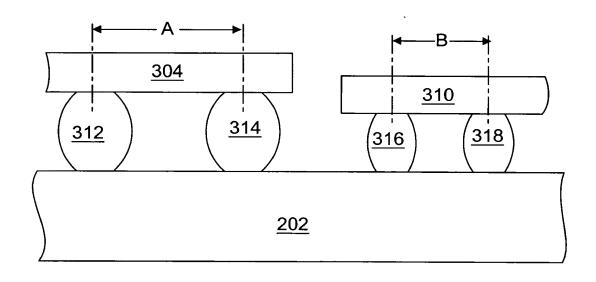


FIGURE 18

TITLE: Melhod of Modular Surrace Mount Technology Solder Volume Optimize Reliability and Fine Pitch Yield

INVENTOR(S): Richard C. Blish II, et al. SERIAL NO. (IF KNOWN): 09/822,562

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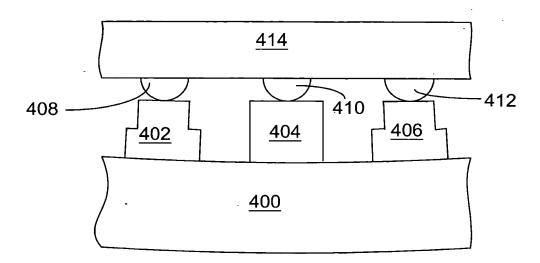


FIGURE 19

